## **Absolute Maximum Ratings**

Stresses beyond the limits listed below may cause permanent damage to the device. Exposure to any Absolute Maximum Rating condition for extended periods may affect device reliability and lifetime.

V <sub>S</sub>	0V to +6V
V <sub>IN</sub>	V <sub>S</sub> - 0.5V to +V <sub>S</sub> +0.5V

#### **Operating Conditions**

Supply Voltage Range	2.5 to 5.5V
Operating Temperature Range	40°C to 85°C
Junction Temperature	150°C
Storage Temperature Range	65°C to 150°C
Lead Temperature (Soldering, 10s)	260°C

#### **Package Thermal Resistance**

θ <sub>JA</sub> (SOIC-8)15	0°C/W
θ <sub>JA</sub> (MSOP-8) 20	W\O°00
θ <sub>JA</sub> (TSOT23-5)21	5°C/W
θ <sub>JA</sub> (TSOT23-6)19	2°C/W
Package thermal resistance ( $\theta_{JA}$ ), JEDEC standard, multest boards, still air.	ti-layer

### **ESD** Protection

SOIC-8 (HBM) ......2.5kV ESD Rating for HBM (Human Body Model) and CDM (Charged Device Model).

## **Electrical Characteristics at +2.7V**

 $T_A$  = 25°C,  $V_S$  = +2.7V,  $R_f$  = 2k\Omega,  $R_L$  = 2k\Omega to  $V_S/2;$  G = 2; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency	Domain Response					
GBWP	-3dB Gain Bandwidth Product			86		MHz
UGBW	Unity Gain Bandwidth <sup>(1)</sup>	$G = +1, V_{OUT} = 0.05V_{pp}$		215		MHz
BW <sub>SS</sub>	-3dB Bandwidth	$G = +2, V_{OUT} = 0.2V_{pp}$		85		MHz
BW <sub>LS</sub>	Large Signal Bandwidth	$G = +2, V_{OUT} = 2V_{pp}$		36		MHz
Time Doma			I	1 1		1
t <sub>R</sub> , t <sub>F</sub>	Rise and Fall Time (1)	V <sub>OUT</sub> = 0.2V step; (10% to 90%)		3.7		ns
ts	Settling Time to 0.1%	V <sub>OUT</sub> = 1V step		40		ns
OS	Overshoot	V <sub>OUT</sub> = 0.2V step		9		%
SR	Slew Rate	G = -1, 2.7V step		130		V/µs
Distortion/N	loise Response		I	11		
HD2	2nd Harmonic Distortion (1)	5MHz, V <sub>OUT</sub> = 1V <sub>pp</sub>		79		dBc
HD3	3rd Harmonic Distortion (1)	$5MHz, V_{OUT} = 1V_{pp}$		82		dBc
THD	Total Harmonic Distortion (1)	$5MHz, V_{OUT} = 1V_{pp}$		77		dB
e <sub>n</sub>	Input Voltage Noise	>1MHz		16		nV/√H
i <sub>n</sub>	Input Current Noise	>1MHz		1.3		pA/√H
X <sub>TALK</sub>	Crosstalk <sup>(1)</sup>	CLC2005, 10MHz		65		dB
DC Perform						
V <sub>IO</sub>	Input Offset Voltage			-1.6		mV
d <sub>VIO</sub>	Average Drift			10		μV/°C
I <sub>B</sub>	Input Bias Current			3		μΑ
dl <sub>B</sub>	Average Drift			7		nA/°C
I <sub>OS</sub>	Input Offset Current			0.1		μΑ
PSRR	Power Supply Rejection Ratio	DC	52	57		dB
A <sub>OL</sub>	Open Loop Gain			75		dB
Is	Supply Current			3.9		mA
	aracteristics (CLC1015)			0.0		1
T <sub>ON</sub>	Turn On Time			150		ns
T <sub>OFF</sub>	Turn Off Time			25		ns
OFFISO	Off Isolation	5MHz, R <sub>L</sub> = 100Ω		75		dB
I <sub>SD</sub>	Disable Supply Current	DIS tied to GND		58	100	μΑ
Input Chara			I	00	100	μ
R <sub>IN</sub>	Input Resistance			4.3		MΩ
C <sub>IN</sub>	Input Capacitance			1.8		pF
	Common Mode Input Range			-0.3 to 1.5		V
CMRR	Common Mode Rejection Ratio	DC, V <sub>CM</sub> = 0 to V <sub>S</sub> - 1.5V		87		dB
Output Cha		DC, VCM = 0 10 VS - 1.5V		07		UD UD
				0.023 to		1
		$R_L = 10k\Omega$ to $V_S / 2$		2.66		V
V <sub>OUT</sub>	Output Swing	$R_L = 2k\Omega$ to $V_S / 2$		0.025 to 2.653		V
		$R_L = 150\Omega$ to $V_S / 2$		0.065 to 2.55		V
				2.55 ±55		mA
I <sub>OUT</sub>	Output Current	-40°C to +85°C		±50		mA
I <sub>SC</sub>	Short Circuit Current	$V_{OUT} = V_S / 2$		±85		mA
.30		•001 - •3' -	2.5	2.7	5.5	V

#### Notes:

1.  $R_f$  = 1k $\Omega$  was used for optimal performance. (For G = +1,  $R_f$  = 0)

## **Electrical Characteristics at +5V**

 $T_A$  = 25°C,  $V_S$  = +5V,  $R_f$  = 2k\Omega,  $R_L$  = 2k\Omega to  $V_S/2;$  G = 2; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Frequency	Domain Response	'				
GBWP	-3dB Gain Bandwidth Product			90		MHz
UGBW	Unity Gain Bandwidth <sup>(1)</sup>	$G = +1, V_{OUT} = 0.05V_{pp}$		260		MHz
BW <sub>SS</sub>	-3dB Bandwidth	$G = +2, V_{OUT} = 0.2V_{pp}$		90		MHz
BW <sub>LS</sub>	Large Signal Bandwidth	$G = +2, V_{OUT} = 2V_{pp}$		40		MHz
Time Doma	in				<u> </u>	
t <sub>R</sub> , t <sub>F</sub>	Rise and Fall Time (1)	V <sub>OUT</sub> = 0.2V step		3.6		ns
t <sub>S</sub>	Settling Time to 0.1%	V <sub>OUT</sub> = 2V step		40		ns
OS	Overshoot	V <sub>OUT</sub> = 0.2V step		7		%
SR	Slew Rate	G = -1, 5V step		145		V/µs
Distortion/N	loise Response					
HD2	2nd Harmonic Distortion (1)	5MHz, V <sub>OUT</sub> = 2V <sub>pp</sub>		71		dBc
HD3	3rd Harmonic Distortion (1)	5MHz, V <sub>OUT</sub> = 2V <sub>pp</sub>		78		dBc
THD	Total Harmonic Distortion (1)	5MHz, V <sub>OUT</sub> = 2V <sub>pp</sub>		70		dB
50	D///	NTSC (3.85MHz), AC-Coupled, $R_L = 150\Omega$		0.06		%
DG	Differential Gain	NTSC (3.85MHz), DC-Coupled, $R_L = 150\Omega$		0.08		%
		NTSC (3.85MHz), AC-Coupled, $R_L = 150\Omega$		0.07		0
DP	Differential Phase	NTSC (3.85MHz), DC-Coupled, $R_L = 150\Omega$		0.06		0
e <sub>n</sub>	Input Voltage Noise	>1MHz		16		nV/√Hz
i <sub>n</sub>	Input Current Noise	>1MHz		1.3		pA/√Hz
X <sub>TALK</sub>	Crosstalk <sup>(1)</sup>	CLC2005, 10MHz		62		dB
DC Perform	ance					
V <sub>IO</sub>	Input Offset Voltage		-8	1.4	8	mV
d <sub>VIO</sub>	Average Drift			10		μV/°C
IB	Input Bias Current		-8	3	8	μA
dl <sub>B</sub>	Average Drift			7		nA/°C
I <sub>OS</sub>	Input Offset Current		-0.8	0.1	0.8	μA
PSRR	Power Supply Rejection Ratio	DC	52	57		dB
A <sub>OL</sub>	Open Loop Gain		68	78		dB
I <sub>S</sub>	Supply Current			4.2	5.2	mA
Disable Cha	aracteristics (CLC1015)					
T <sub>ON</sub>	Turn On Time			150		ns
T <sub>OFF</sub>	Turn Off Time			25		ns
OFFISO	Off Isolation	5MHz, R <sub>L</sub> = 100Ω		75		dB
I <sub>SD</sub>	Disable Supply Current	DIS tied to GND		127	170	μA
Input Chara	acteristics					
R <sub>IN</sub>	Input Resistance			4.3		ΜΩ
C <sub>IN</sub>	Input Capacitance			1.8		pF
CMIR	Common Mode Input Range			-0.3 to 3.8		V
CMRR	Common Mode Rejection Ratio	DC, $V_{CM} = 0$ to $V_S - 1.5V$	72	87		dB

## **Electrical Characteristics at +5V Continued**

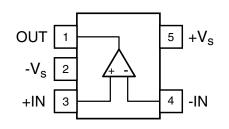
 $T_A$  = 25°C,  $V_S$  = +5V,  $R_f$  = 2k $\Omega,~R_L$  = 2k $\Omega$  to  $V_S/2;~G$  = 2; unless otherwise noted.

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Output Cha	aracteristics					
		$R_L = 10k\Omega$ to $V_S/2$		0.027 to 4.97		V
V <sub>OUT</sub> Output Swing	$R_L = 2k\Omega$ to $V_S/2$		0.036 to 4.953		V	
		$R_L = 150\Omega$ to $V_S / 2$	0.3	0.12 to 4.8	4.625	V
	Quite it Current			±55		mA
IOUT	Output Current	-40°C to +85°C		±50		mA
I <sub>SC</sub>	Short Circuit Current	$V_{OUT} = V_S / 2$		±85		mA
VS	Power Supply Operating Range		2.5	5	5.5	V

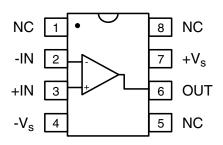
Notes:

1.  $R_f = 1k\Omega$  was used for optimal performance. (For G = +1,  $R_f = 0$ )

# CLC1005 Pin Configurations



#### SOIC-8



## **CLC1005 Pin Assignments**

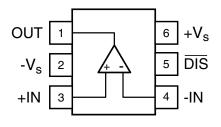
#### TSOT-5

Pin No.	Pin Name	Description
1	OUT	Output
2	-V <sub>S</sub>	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	+V <sub>S</sub>	Positive supply

#### SOIC-8

Pin No.	Pin Name	Description
1	NC	No Connect
2	-IN	Negative input
3	+IN	Positive input
4	-V <sub>S</sub>	Negative supply
5	NC	No Connect
6	OUT	Output
7	+V <sub>S</sub>	Positive supply
8	NC	No Connect

# CLC1015 Pin Configurations

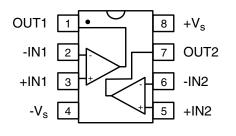


## **CLC1015 Pin Assignments**

#### TSOT-6

Pin No.	Pin Name	Description
1	OUT	Output
2	-V <sub>S</sub>	Negative supply
3	+IN	Positive input
4	-IN	Negative input
5	DIS	Disable pin. Enabled if pin is left open or tied to $+V_S$ , disabled if pin is tied to $-V_S$ (which is GND in a single supply application.)
6	+V <sub>S</sub>	Positive supply

## CLC2005 Pin Configuration SOIC-8 / MSOP-8



## **CLC2005 Pin Assignments**

#### SOIC-8 / MSOP-8

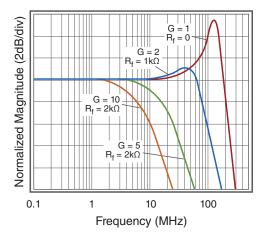
Pin No.	Pin Name	Description	
1	OUT1	Output, channel 1	
2	-IN1	Negative input, channel 1	
3	+IN1	Positive input, channel 1	
4	-V <sub>S</sub>	Negative supply	
5	+IN2	Positive input, channel 2	
6	-IN2	Negative input, channel 2	
7	OUT2	Output, channel 2	
8	+V <sub>S</sub>	Positive supply	

 $T_A$  = 25°C,  $V_S$  = +5V,  $R_L$  = 2k $\Omega$  to  $V_S/2,~G$  = +2,  $R_F$  = 2k $\Omega;$  unless otherwise noted.

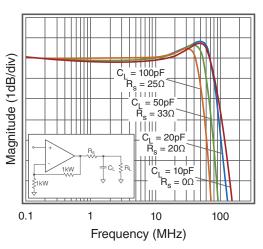
Non-Inverting Frequency Response  $V_S = +5V$ 

(NipO) apprint (Constrained by the second s

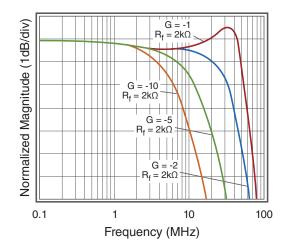
Non-Inverting Frequency Response  $V_S = +2.7V$ 



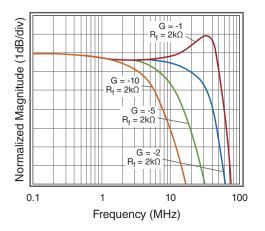
Frequency Response vs CL

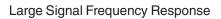


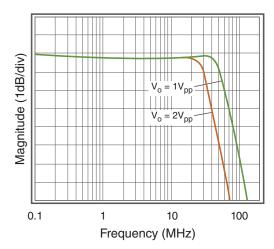
Inverting Frequency Response  $V_S = +5V$ 



Inverting Frequency Response  $V_S = +2.7V$ 

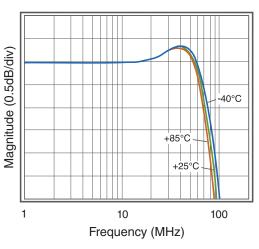




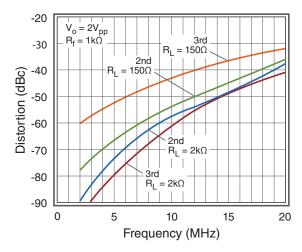


 $T_A = 25^{\circ}C$ ,  $V_S = +5V$ ,  $R_L = 2k\Omega$  to  $V_S/2$ , G = +2,  $R_F = 2k\Omega$ ; unless otherwise noted.

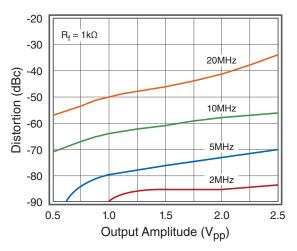
Frequency Response vs. Temperature



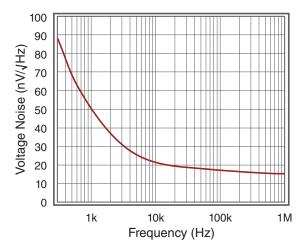
2nd & 3rd Harmonic Distortion  $V_S = +5V$ 



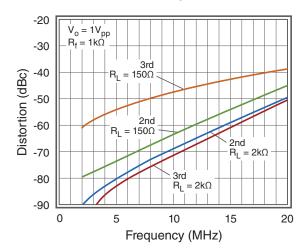
2nd Harmonic Distortion vs  $V_O$ 



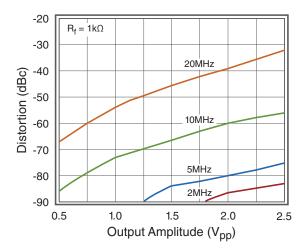
Input Voltage Noise vs Frequency



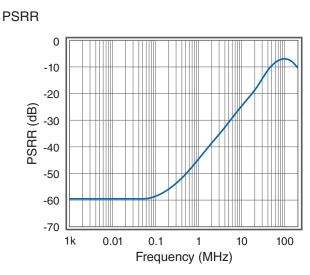
2nd & 3rd Harmonic Distortion  $V_S = +2.7V$ 



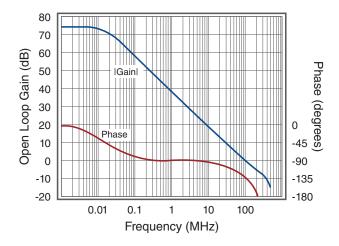
<sup>3</sup>rd Harmonic Distortion vs V<sub>O</sub>



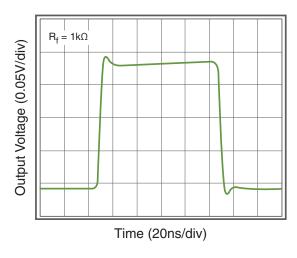
 $T_A = 25^{\circ}C$ ,  $V_S = +5V$ ,  $R_L = 2k\Omega$  to  $V_S/2$ , G = +2,  $R_F = 2k\Omega$ ; unless otherwise noted.

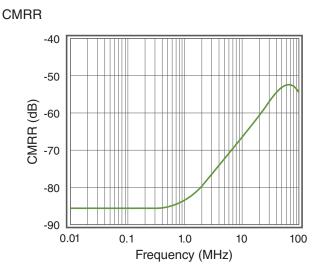


Open Loop Gain & Phase vs. Frequency

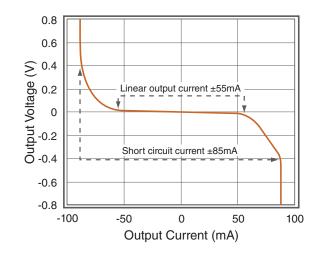


Small Signal Pulse Response  $V_S = +5V$ 

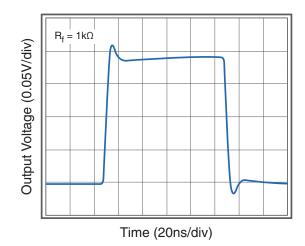








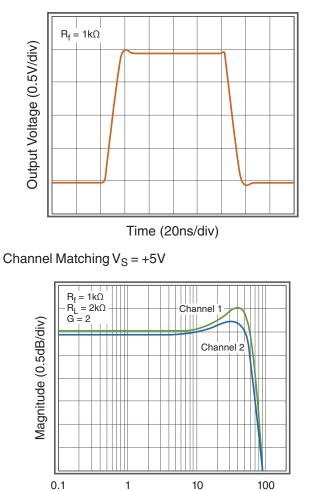
Small Signal Pulse Response  $V_S = +2.7V$ 



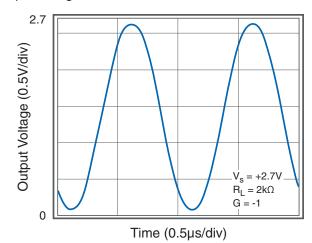
 $T_A = 25^{\circ}C$ ,  $V_S = +5V$ ,  $R_L = 2k\Omega$  to  $V_S/2$ , G = +2,  $R_F = 2k\Omega$ ; unless otherwise noted.

Large Signal Pulse Response  $V_S = +5V$ 

**Output Swing** 



Frequency (MHz)



#### **Application Information**

#### **General Description**

The CLC1005, CLC1015, and CLC2005 are single supply, general purpose, voltage-feedback amplifiers fabricated on a complementary bipolar process using a patented topography. They feature a rail-to-rail output stage and are unity gain stable. Both gain bandwidth and slew rate are insensitive to temperature.

The common mode input range extends to 300mV below ground and to 1.2V below V<sub>s</sub>. Exceeding these values will not cause phase reversal. However, if the input voltage exceeds the rails by more than 0.5V, the input ESD devices will begin to conduct. The output will stay at the rail during this overdrive condition.

The design is short circuit protected and offers "soft" saturation protection that improves recovery time.

Figures 1, 2, and 3 illustrate typical circuit configurations for non-inverting, inverting, and unity gain topologies for dual supply applications. They show the recommended bypass capacitor values and overall closed loop gain equations. Figure 4 shows the typical non-inverting gain circuit for single supply applications.

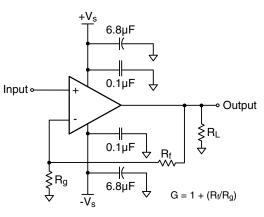


Figure 1: Typical Non-Inverting Gain Circuit

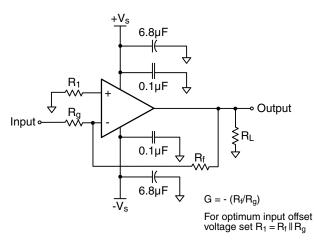


Figure 2: Typical Inverting Gain Circuit

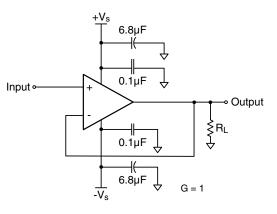


Figure 3: Unity Gain Circuit

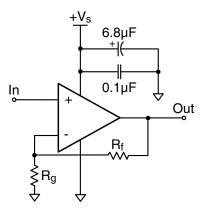


Figure 4: Single Supply Non-Inverting Gain Circuit

At non-inverting gains other than G = +1, keep R<sub>g</sub> below 1k $\Omega$  to minimize peaking; thus for optimum response at a gain of +2, a feedback resistor of 1k $\Omega$  is recommended. Figure 5 illustrates the CLC1005, CLC1015 and CLC2005 frequency response with both 1k $\Omega$  and 2k $\Omega$  feedback resistors.

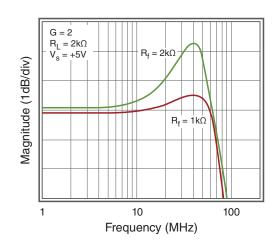


Figure 5: Frequency Response vs. Rf

#### **Overdrive Recovery**

For an amplifier, an overdrive condition occurs when the output and/or input ranges are exceeded. The recovery time varies based on whether the input or output is overdriven and by how much the ranges are exceeded. The CLC1005, CLC1015, and CLC2005 will typically recover in less than 20ns from an overdrive condition. Figure 6 shows the CLC2005 in an overdriven condition.

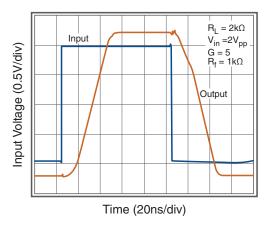


Figure 6: Overdrive Recovery

#### **Enable/Disable Function**

The CLC1015 offers an active-low disable pin that can be used to lower its supply current. Leave the pin floating to enable to part. Pull the disable pin to the negative supply (which is ground in a single supply application) to disable the output. During the disable condition, the nominal supply current will drop below  $127\mu$ A and the output will be at a high impedance with about 2pF capacitance.

#### **Power Dissipation**

Power dissipation should not be a factor when operating under the stated  $2k\Omega$  load condition. However, applications with low impedance, DC coupled loads should be analyzed to ensure that maximum allowed junction temperature is not exceeded. Guidelines listed below can be used to verify that the particular application will not cause the device to operate beyond it's intended operating range.

Maximum power levels are set by the absolute maximum junction rating of 150°C. To calculate the junction temperature, the package thermal resistance value Theta<sub>JA</sub> ( $\theta_{JA}$ ) is used along with the total die power dissipation.

$$T_{Junction} = T_{Ambient} + (\theta_{JA} \times P_D)$$

Where  $\mathsf{T}_{\mathsf{Ambient}}$  is the temperature of the working environment.

In order to determine  $\mathsf{P}_\mathsf{D}$ , the power dissipated in the load

needs to be subtracted from the total power delivered by the supplies.

$$P_D = P_{supply} - P_{load}$$

Supply power is calculated by the standard power equation.

$$\label{eq:product} \begin{split} \mathsf{P}_{supply} &= \mathsf{V}_{supply} \times \mathsf{I}_{\mathsf{RMSsupply}} \\ \mathsf{V}_{supply} &= \mathsf{V}_{\mathsf{S}\text{+}} - \mathsf{V}_{\mathsf{S}\text{-}} \end{split}$$

Power delivered to a purely resistive load is:

$$P_{load} = ((V_{load})_{RMS^2})/Rload_{eff}$$

The effective load resistor ( $Rload_{eff}$ ) will need to include the effect of the feedback network. For instance,

Rload<sub>eff</sub> in Figure 3 would be calculated as:

$$R_L \parallel (R_f + R_g)$$

These measurements are basic and are relatively easy to perform with standard lab equipment. For design purposes however, prior knowledge of actual signal levels and load impedance is needed to determine the dissipated power. Here,  $P_D$  can be found from

$$P_D = P_{Quiescent} + P_{Dynamic} - P_{load}$$

Quiescent power can be derived from the specified  $I_{\rm S}$  values along with known supply voltage,  $V_{\text{supply}}.$  Load power can be calculated as above with the desired signal amplitudes using:

The dynamic power is focused primarily within the output stage driving the load. This value can be calculated as:

$$P_{Dynamic} = (V_{S+} - V_{load})_{RMS} \times (I_{load})_{RMS}$$

Assuming the load is referenced in the middle of the power rails or  $V_{supply}/2$ .

The CLC1015 is short circuit protected. However, this may not guarantee that the maximum junction temperature (+150°C) is not exceeded under all conditions. Figure 7 shows the maximum safe power dissipation in the package vs. the ambient temperature for the packages available.

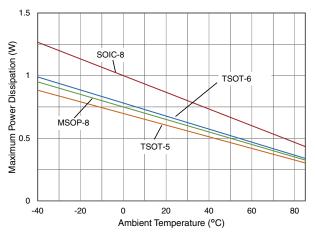


Figure 7. Maximum Power Derating

#### **Driving Capacitive Loads**

Increased phase delay at the output due to capacitive loading can cause ringing, peaking in the frequency response, and possible unstable behavior. Use a series resistance,  $R_S$ , between the amplifier and the load to help improve stability and settling performance. Refer to Figure 8.

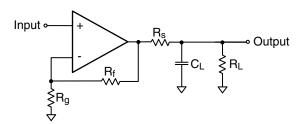


Figure 8. Addition of R<sub>S</sub> for Driving Capacitive Loads

Table 1 provides the recommended  $R_S$  for various capacitive loads. The recommended  $R_S$  values result in approximately <1dB peaking in the frequency response.

C <sub>L</sub> (pF)	R <sub>S</sub> (Ω)	-3dB BW (MHz)
22pF	0	118
47pF	15	112
100pF	15	91
492pF	6.5	59

Table 1: Recommended R<sub>S</sub> vs. C<sub>L</sub>

For a given load capacitance, adjust  ${\sf R}_S$  to optimize the tradeoff between settling time and bandwidth. In general, reducing  ${\sf R}_S$  will increase bandwidth at the expense of additional overshoot and ringing.

#### **Layout Considerations**

General layout and supply bypassing play major roles in high frequency performance. Resurgent has evaluation boards to use as a guide for high frequency layout and as an aid in device testing and characterization. Follow the steps below as a basis for high frequency layout:

- Include 6.8µF and 0.1µF ceramic capacitors for power supply decoupling
- Place the 6.8µF capacitor within 0.75 inches of the power pin
- Place the 0.1µF capacitor within 0.1 inches of the power pin
- Remove the ground plane under and around the part, especially near the input and output pins to reduce parasitic capacitance
- Minimize all trace lengths to reduce series inductances

Refer to the evaluation board layouts below for more information.

#### **Evaluation Board Information**

The following evaluation boards are available to aid in the testing and layout of these devices:

Evaluation Board #	Products
CEB002	CLC1005 and CLC1015 in TSOT
CEB003	CLC1005 in SOIC
CEB006	CLC2005 in SOIC
CEB010	CLC2005 in MSOP

#### **Evaluation Board Schematics**

Evaluation board schematics and layouts are shown in Figures 9-18. These evaluation boards are built for dualsupply operation. Follow these steps to use the board in a single-supply application:

- 1. Short -V $_{\rm S}$  to ground.
- 2. Use C3 and C4, if the  $-V_S$  pin of the amplifier is not directly connected to the ground plane.

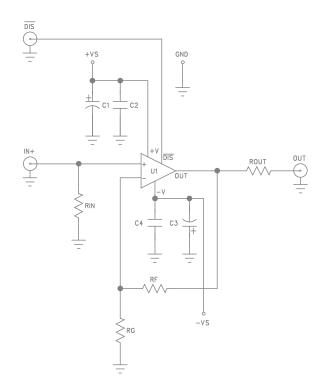


Figure 9. CEB002 and CEB003 Schematic

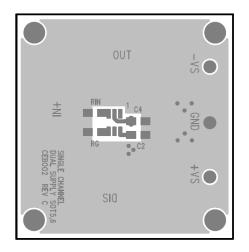


Figure 10. CEB002 Top View

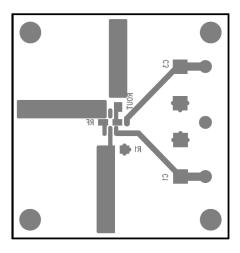


Figure 11. CEB002 Bottom View

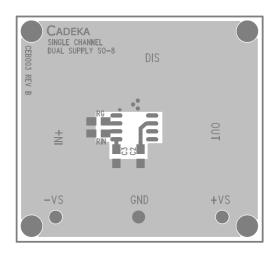


Figure 12. CEB003 Top View

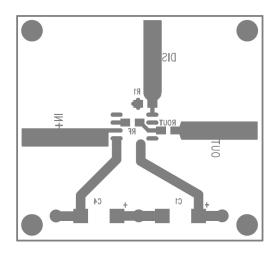


Figure 13. CEB003 Bottom View

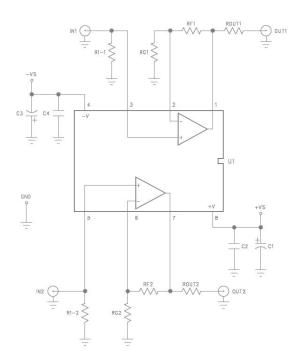


Figure 14. CEB006 & CEB010 Schematic

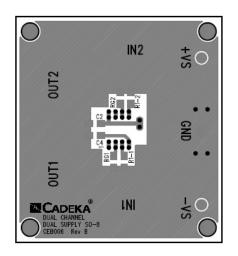


Figure 15. CEB006 Top View

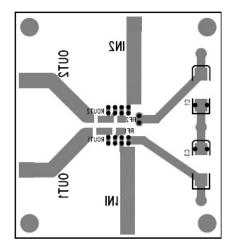


Figure 16. CEB006 Bottom View

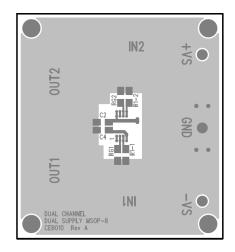


Figure 17. CEB010 Top View

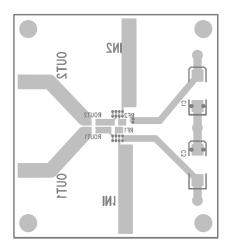
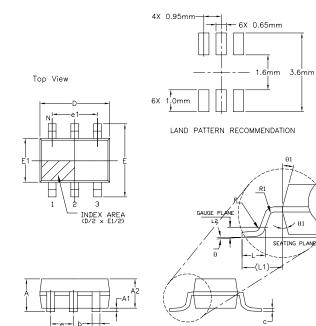


Figure 18. CEB010 Bottom View

## **Mechanical Dimensions**

## TSOT-6 Package



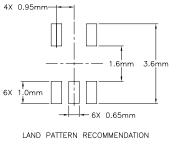
Front View

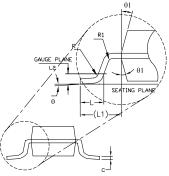
6 PIN TSOT (OPTION 2)						
SYMBOLS	DIMENSION IN MM (Control Unit)			DIMENSION IN INCH (Reference Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.75	—	0.80	0.030	—	0.031
A1	0.00	—	0.05	0.000	—	0.002
A2	0.70	0.75	0.78	0.028	0.036	0.031
b	0.35		0.50	0.012		0.020
с	0.10	—	0.20	0.003		0.008
D	2.90 BSC			0.114 BSC		
E	2.80 BSC			0.110 BSC		
E1	1.60 BSC			0.063 BSC		
e	0.95 BSC			0.038 BSC		
e1	1.90 BSC			0.075 BSC		
L	0.37	0.45	0.60	0.012	0.018	0.024
L1	0.60 REF			0.024 REF		
L2	0.25 BSC			0.010 BSC		
R	0.10	—	_	0.004	_	_
R1	0.10	—	0.25	0.004	—	0.010
θ	0*	4*	8*	0*	4*	8*
θ1	4*	10*	12*	4°	10°	12°
N	6				6	

#### **TSOT-5 Package**

Side View

Top View





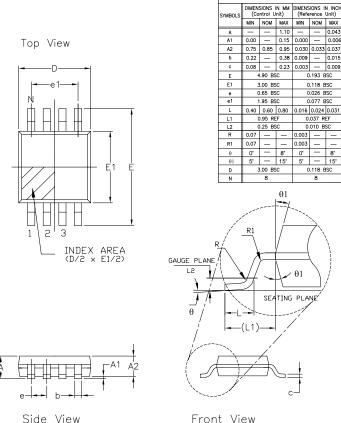
Front View

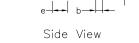
A2 A1

5 Pin TSOT (OPTION 2)						
SYMBOLS	DIMENSION IN MM (Control Unit)			DIMENSION IN INCH (Reference Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.75	—	0.80	0.030	—	0.031
A1	0.00	—	0.05	0.000	-	0.002
A2	0.70	0.75	0.78	0.028	0.030	0.031
b	0.35	—	0.50	0.012	-	0.020
с	0.10	—	0.20	0.003	—	0.008
D	2.90 BSC			0.114 BSC		
E	2.80 BSC			0.110 BSC		
E1	1.60 BSC			0.063 BSC		
е	0.95 BSC			0.038 BSC		
e1	1.90 BSC			0.075 BSC		
L	0.37	0.45	0.60	0.012	0.018	0.024
L1	0.60 REF			0.024 REF		
L2	0.25 BSC			0.010 BSC		
R	0.10	_	_	0.004	_	_
R1	0.10	—	0.25	0.004	_	0.010
θ	0.	4*	8'	0,	4'	8'
θ1	4.	10"	12	4'	10	12
N	5				5	

Side View

#### **MSOP-8 Package**

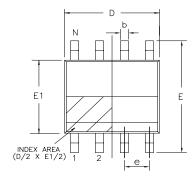




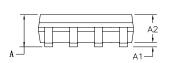
Front View

8 Pin MSOP JEDEC MO-187 Variation AA

**SOIC-8 Package** 

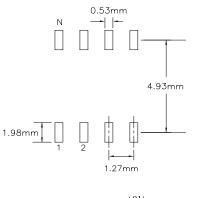


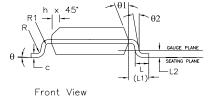
Top View



Side View

RECOMMENDED PCB LAND PATTERN





8 Pin	SOICN	JEDE	EC MS-	·012 `	Variatio	n AA	
SYMBOLS	DIMENSIONS IN MM (Control Unit)				SIONS IN INCH erence Unit)		
	MIN	NOM	MAX	MIN	NOM	MAX	
А	1.35	—	1.75	0.053		0.069	
A1	0.10	—	0.25	0.004	_	0.010	
A2	1.25	—	1.65	0.049	—	0.065	
b	0.31		0.51	0.012	_	0.020	
с	0.17	_	0.25	0.007	_	0.010	
E	6.00 BSC			0.236 BSC			
E1	3.90 BSC			0.154 BSC			
е	1.27 BSC			0.050 BSC			
h	0.25	—	0.50	0.010	_	0.020	
L	0.40	_	1.27	0.016	_	0.050	
L1	1.04 REF			0.041 REF			
L2	0.25 BSC			0.010 BSC			
R	0.07	—	_	0.003	_	—	
R1	0.07	_	_	0.003	_	—	
θ	0*	_	8*	0°	—	8'	
θ1	5°	—	15°	5°	_	15°	
θ2	0.	—	_	0°	_	_	
D	4.90 BSC			0.193 BSC			
Ν	8				8		

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## **Ordering Information**

Part Number	Package	Green	Operating Temperature Range	Packaging
CLC1005 Ordering Information	1			
CLC1005IST5X	TSOT-5	Yes	-40°C to +85°C	Tape & Reel
CLC1005IST5MTR	TSOT-5	Yes	-40°C to +85°C	Mini Tape & Reel
CLC1005IST5EVB	Evaluation Board	N/A	N/A	N/A
CLC1005ISO8X	SOIC-8	Yes	-40°C to +85°C	Tape & Reel
CLC1005ISO8MTR	SOIC-8	Yes	-40°C to +85°C	Mini Tape & Reel
CLC1005ISO8EVB	Evaluation Board	N/A	N/A	N/A
CLC1015 Ordering Information				
CLC1015IST6X	TSOT-6	Yes	-40°C to +85°C	Tape & Reel
CLC1015IST6MTR	TSOT-6	Yes	-40°C to +85°C	Mini Tape & Reel
CLC1015IST6EVB	Evaluation Board	N/A	N/A	N/A
CLC2005 Ordering Information	ı			
CLC2005ISO8X*	SOIC-8	Yes	-40°C to +85°C	Tape & Reel
CLC2005ISO8MTR*	SOIC-8	Yes	-40°C to +85°C	Mini Tape & Reel
CLC2005ISO8EVB*	Evaluation Board	N/A	N/A	N/A
CLC2005IMP8X*	MSOP-8	Yes	-40°C to +85°C	Tape & Reel
CLC2005IMP8MTR*	MSOP-8	Yes	-40°C to +85°C	Mini Tape & Reel
CLC2005IMP8EVB*	Evaluation Board	N/A	N/A	N/A

Moisture sensitivity level for all parts is MSL-1. Mini tape and reel quantity is 250.

\*Contact Resurgent Semiconductor for availability.

## **Revision History**

Revision	Date	Description
2D (ECN 1513-01)	March 2015	Reformat into Exar data sheet template. Updated ordering information table to include MTR and EVB part numbers. Updated thermal resistance numbers and package outline drawings. Added CLC1015 back into data sheet.
2D.R	July 2018	Updated to Resurgent Semiconductor.

#### For Further Assistance:

#### www.resurgentsemi.net

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